

Abstract of the Disclosure:

A module serves as a heat sink for semiconductor components.

The module includes a diamond/composite substrate that carries a multilayer coating on at least one substrate surface and a

5 housing frame made from ceramics which is soldered onto the substrate. The module excellently fulfills the demands imposed on it, namely a good ability for areally joining to the semiconductor component, a high heat transfer through the joining zone and a good electrical conductivity of the module
10 in the joining zone.

WHS:nt - SB-519F//9/19/2003